

IGBT Modules

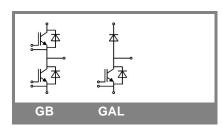
SKM 150GB123D SKM 150GAL123D

Features

- MOS input (voltage controlled)
- N channel, Homogeneous Si
- · Low inductance case
- Very low tail current with low temperature dependence
- High short circuit capability, self limiting to 6 x I_{cnom}
- · Latch-up free
- Fast & soft inverse CAL diodes
- Isolated copper baseplate using DCB Direct Copper Bonding
- Large clearance (12 mm) and creepage distances (20 mm)

Typical Applications*

- AC inverter drives
- UPS



Absolute Maximum Ratings T _c = 25 °C, unless otherwise specific					
Symbol	Conditions		Values	Units	
IGBT					
V_{CES}	T _j = 25 °C		1200	V	
I _C	T _j = 150 °C	T _{case} = 25 °C	150	Α	
		T _{case} = 80 °C	110	Α	
I _{CRM}	I _{CRM} =2xI _{Cnom}		200	Α	
V_{GES}			± 20	V	
t _{psc}	V_{CC} = 600 V; $V_{GE} \le 20$ V; $V_{CES} < 1200$ V	T _j = 125 °C	10	μs	
Inverse D	Piode				
I _F	T _j = 150 °C	T_{case} = 25 °C	150	Α	
		T _{case} = 80 °C	100	Α	
I _{FRM}	I _{FRM} =2xI _{Fnom}		200	Α	
I _{FSM}	t _p = 10 ms; sin.	T _j = 150 °C	1100	Α	
Freewhee	eling Diode				
I _F	T _j = 150 °C	T_{case} = 25 °C	200	Α	
		T _{case} = 80 °C	135	Α	
I _{FRM}			300	Α	
I _{FSM}	t _p = 10 ms; sin.	T _j = 150 °C	1440	Α	
Module					
I _{t(RMS)}			500	Α	
T _{vj}			- 40 + 150	°C	
T _{stg}			-40 + 125	°C	
V _{isol}	AC, 1 min.		2500	V	

Characteristics T _c = 25 °C, unless otherwise specific					ecified	
Symbol	Conditions		min.	typ.	max.	Units
IGBT						
$V_{GE(th)}$	$V_{GE} = V_{CE}$, $I_C = 4 \text{ mA}$		4,5	5,5	6,5	V
I _{CES}	$V_{GE} = 0 V, V_{CE} = V_{CES}$	T _j = 25 °C		0,1	0,3	mA
		T _j = 125 °C				mA
V _{CE0}		T _j = 25 °C		1,4	1,6	V
		T _j = 125 °C		1,6	1,8	V
r _{CE}	V _{GE} = 15 V	T _j = 25°C		11	14	mΩ
		T _j = 125°C		15	19	mΩ
V _{CE(sat)}	I _{Cnom} = 100 A, V _{GE} = 15 V	T _j = °C _{chiplev.}		2,5	3	V
C _{ies}				6,5	8,5	nF
C _{oes}	$V_{CE} = 25, V_{GE} = 0 V$	f = 1 MHz		1	1,5	nF
C _{res}				0,5	0,6	nF
Q_G	V _{GE} = -8V - +20V			1000		nC
R _{Gint}	T _j = °C			2,5		Ω
t _{d(on)}				160	320	ns
t _r	R_{Gon} = 6,8 Ω	V _{CC} = 600V		80	160	ns
E _{on}		I _C = 100A		13		mJ
t _{d(off)}	R_{Goff} = 6,8 Ω	T _j = 125 °C		400	520	ns
t _f		$V_{GE} = \pm 15V$		70	100	ns
E _{off}				11		mJ
R _{th(j-c)}	per IGBT				0,15	K/W



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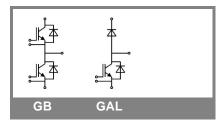
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Characte	ristics					
Symbol	Conditions		min.	typ.	max.	Units
Inverse D	Diode					•
$V_F = V_{EC}$	I_{Fnom} = 100 A; V_{GE} = 0 V			2	2,5	V
		$T_j = 125 ^{\circ}C_{\text{chiplev.}}$ $T_j = 25 ^{\circ}C$		1,8		V
V_{F0}				1,1	1,2	V
		T _j = 125 °C				V
r _F		T _j = 25 °C		9	13	mΩ
		T _j = 125 °C				mΩ
I _{RRM}	I _F = 100 A	T _j = 125 °C		50		A
Q _{rr}	di/dt = 1000 A/µs			5		μC
E _{rr}	V _{GE} = 0 V; V _{CC} = 600 V					mJ
$R_{th(j-c)D}$	per diode				0,3	K/W
	eling Diode	ı				•
$V_F = V_{EC}$	I _{Fnom} = 150 A; V _{GE} = 0 V			2	2,5	V
		$T_j = 125 ^{\circ}C_{\text{chiplev.}}$ $T_j = 25 ^{\circ}C$		1,8		V
V_{F0}				1,1	1,2	V
		T _j = 125 °C				V
r _F		T _j = 25 °C		6	8,7	V
		T _j = 125 °C				V
I _{RRM}	I _F = 100 A	T _j = 25 °C		40 5		A
Q _{rr}	\/ -0\/:\/ -600\/			5		μC
E _{rr}	V _{GE} = 0 V; V _{CC} = 600 V					mJ
$R_{th(j-c)FD}$	per diode				0,25	K/W
Module	i.	ı				•
L _{CE}				15	20	nH
R _{CC'+EE'}	res., terminal-chip	T _{case} = 25 °C		0,35		mΩ
		T _{case} = 125 °C		0,5		mΩ
$R_{\text{th(c-s)}}$	per module				0,038	K/W
M _s	to heat sink M6		3		5	Nm
M _t	to terminals M6		2,5		5	Nm
w					325	g

This is an electrostatic discharge sensitive device (ESDS), international standard IEC 60747-1, Chapter IX.

* The specifications of our components may not be considered as an assurance of component characteristics. Components have to be tested for the respective application. Adjustments may be necessary. The use of SEMIKRON products in life support appliances and systems is subject to prior specification and written approval by SEMIKRON. We therefore strongly recommend prior consultation of our personal.





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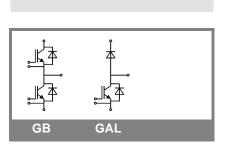
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Z _{th}			
Symbol	Conditions	Values	Units
Z _{th/i o)l}			
Z th(j-c)l R _i	i = 1	105	mk/W
R_{i}	i = 2	35	mk/W
R _i	i = 3	8	mk/W
R_i	i = 4	2	mk/W
tau _i	i = 1	0,03	s
tau _i	i = 2	0,03	S
tau _i	i = 3	0,0014	S
tau _i	i = 4	0,0001	s
Z,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,			
Z R _i th(j-c)D	i = 1	210	mk/W
Ri	i = 2	70	mk/W
R_{i}	i = 3	16	mk/W
R _i	i = 4	4	mk/W
tau _i	i = 1	0,0623	s
tau _i	i = 2	0,0083	s
tau _i	i = 3	0,003	s
tau _i	i = 4	0,0002	s

